

Charles University Prague  
Institute of Particle and Nuclear Physics

# Tests Of Laser In Silicon Detectors

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## Progress of laser tests in Prague

1. Testing algorithms of strip detectors tuned
2. Set of standard tests and analyses: focusing, strip response, charge sharing
3. Different wavelengths: 650nm and 1060nm used
4. Angle (skew) scans
5. Optical head for direct beam power measurements in progress
6. Simulations of laser beam in Si (Zbyněk Drásal – next talk)
7. Deeper understanding of laser beam interaction with Si detectors
8. Preparing analysis macros



## Testing procedures of strip detectors

The test system integrates:

- Short pulsed lasers 650 and 1060 nm (CERN)
- DAQ (VME – NI PCI-VME )
- oscilloscope (GPIB)
- pulse generator (GPIB)
- positioning stages 3D-2R (USB)
- 2 power supplies (USB-RS232)

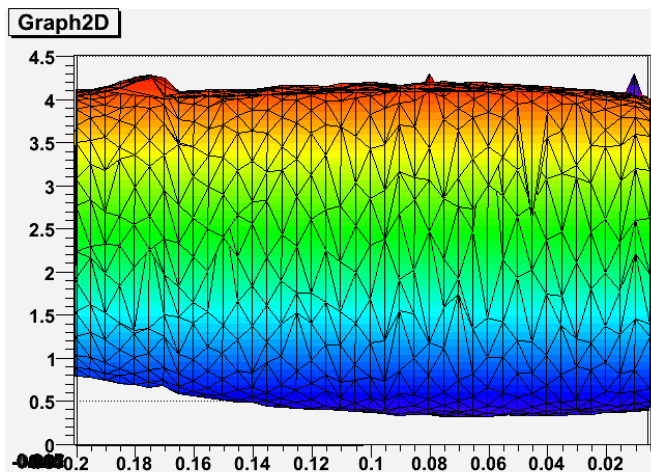
ROOT based software allows

- High voltage (bias) control
- Focusing algorithms – rough, fine
- Position scans
- Timing scans
- Angle scans including deep focusing
- Environmental monitoring (temperature, humidity, power drops, bias drops, remote access and full processing from any place (VNC), automatic emergency system)

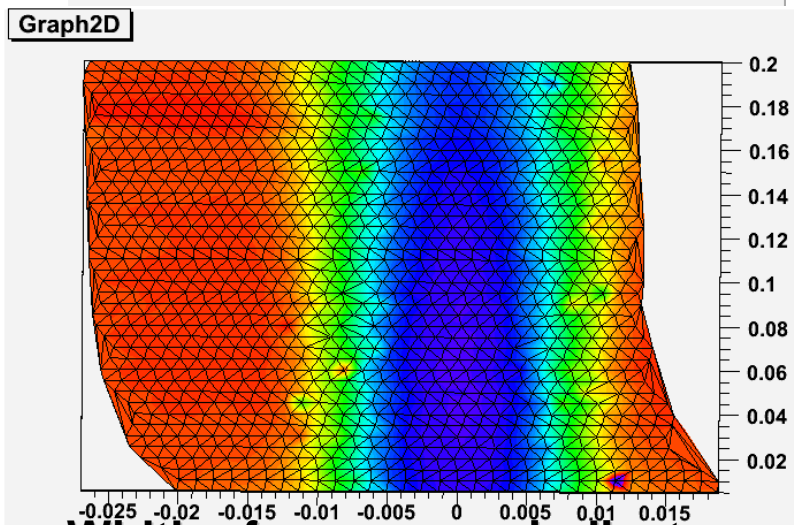


# Set of standard tests and analyses: focusing, strip response, charge sharing

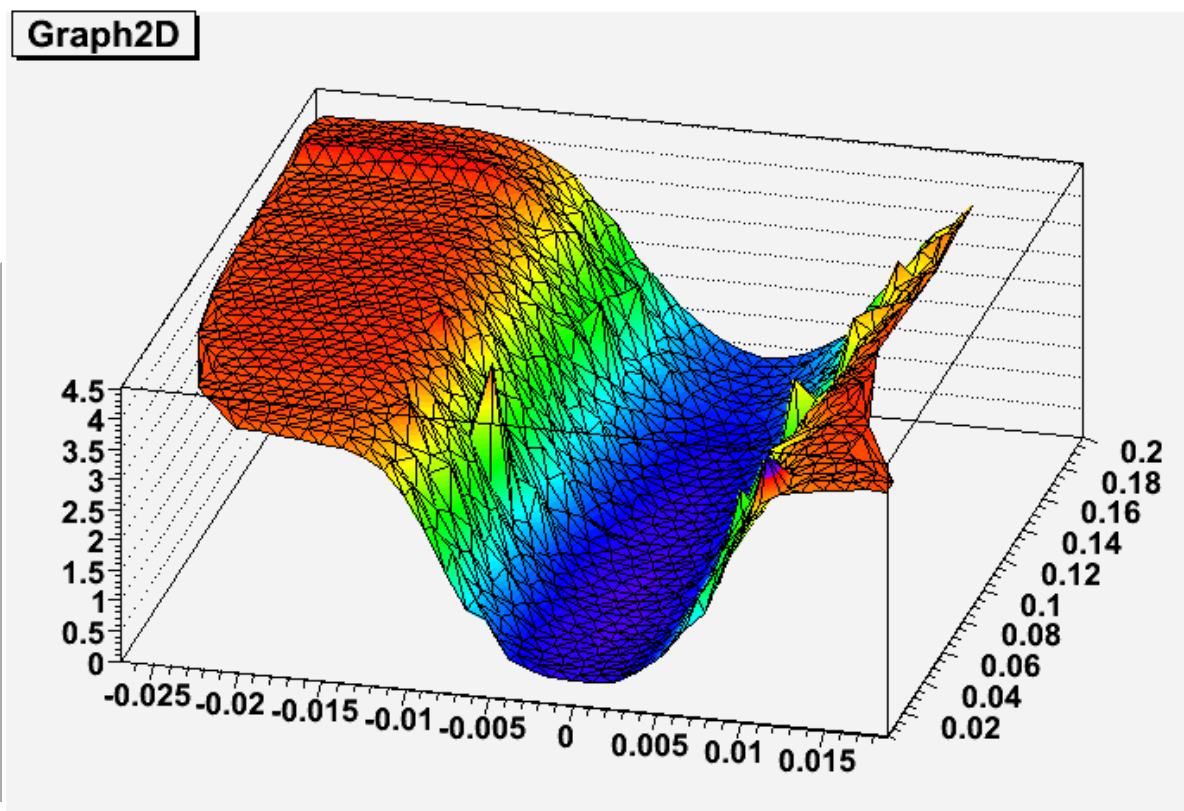
Example of focusing  
matrix



Detail of minima (flat in 60µm range)



Width of green area indicates  
laser focusing width





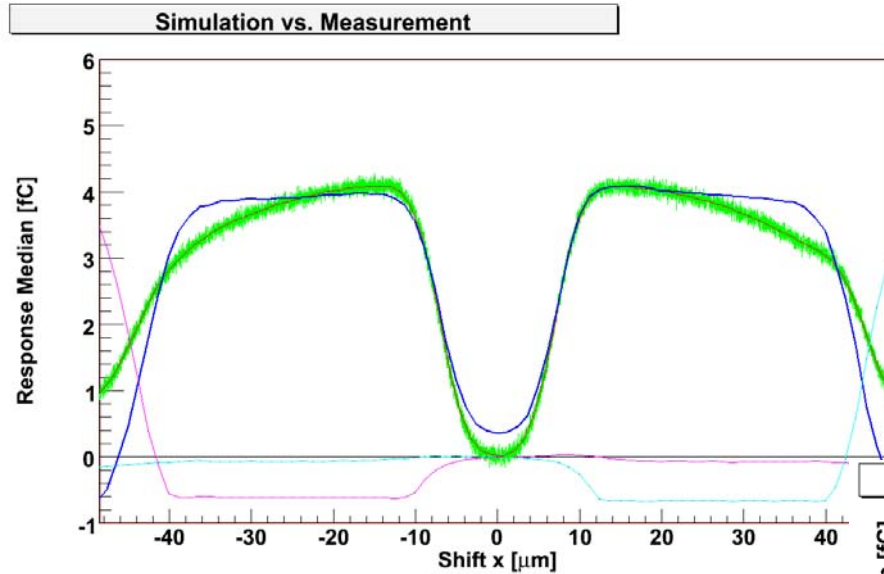
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## Simulations of laser beam in Si

Subject of a separate talk by Zbyněk Drásal

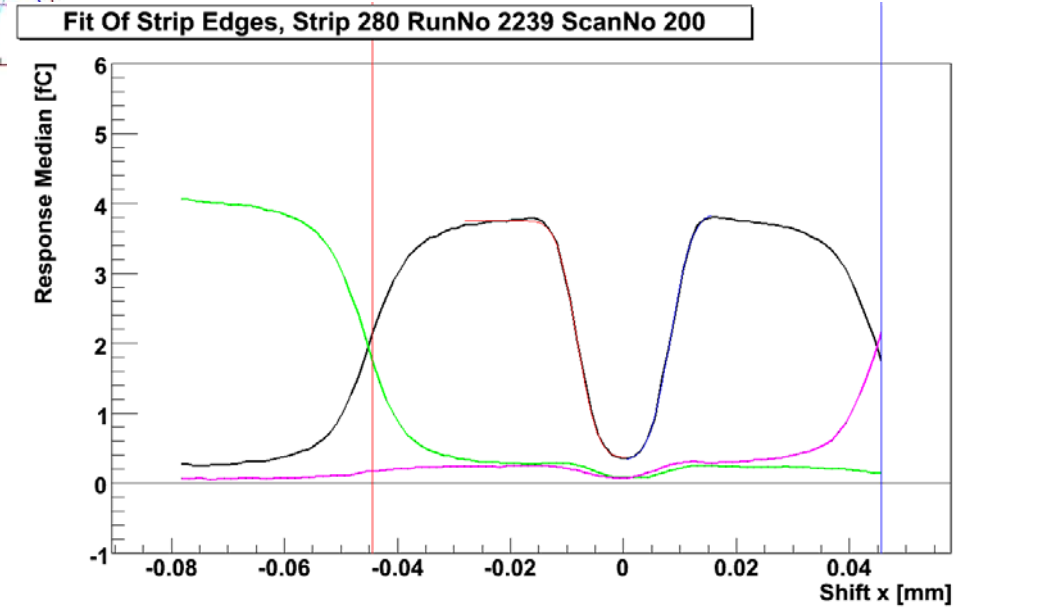


## Different wavelengths: 650nm and 1060nm



CiS detector: wavelength 650nm,  
differences from simulations, negative  
charge induced in neighbour strips

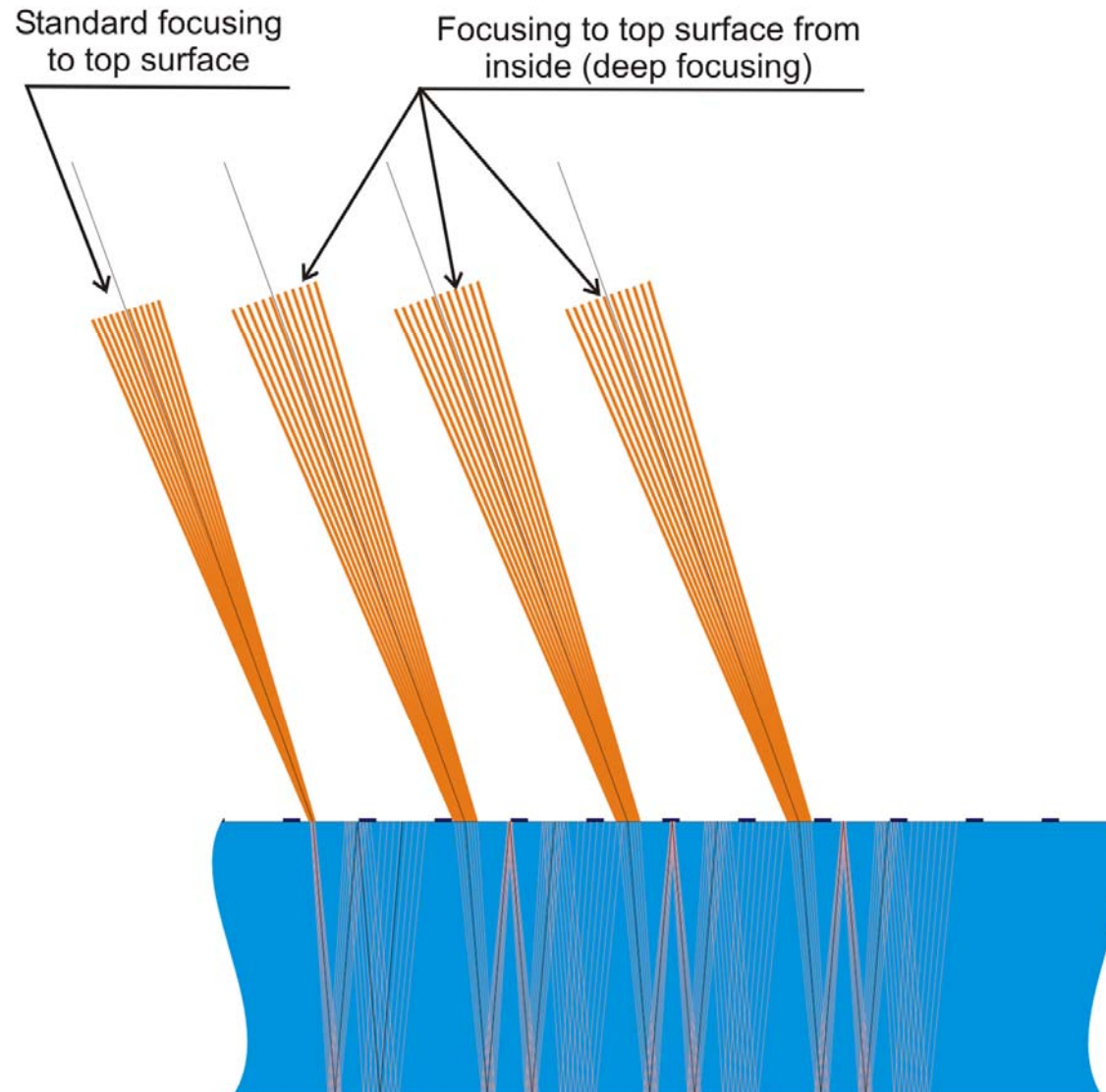
CiS detector: 1060 wavelength – in  
very good agreement with simulations





# Angle (skew) scans (1)

Tilt laser beam

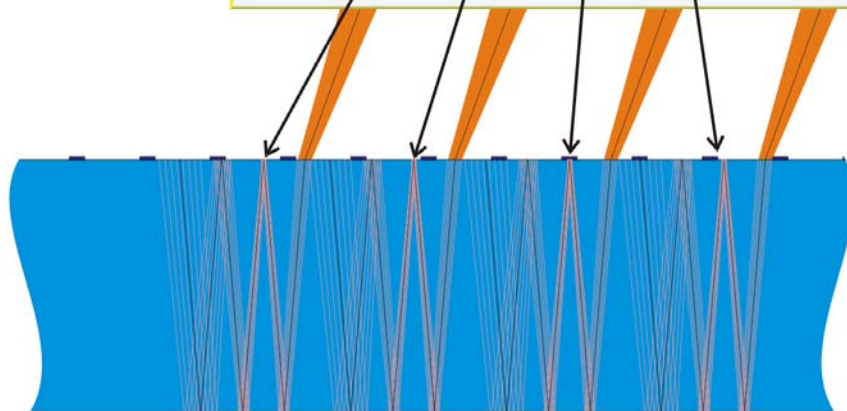
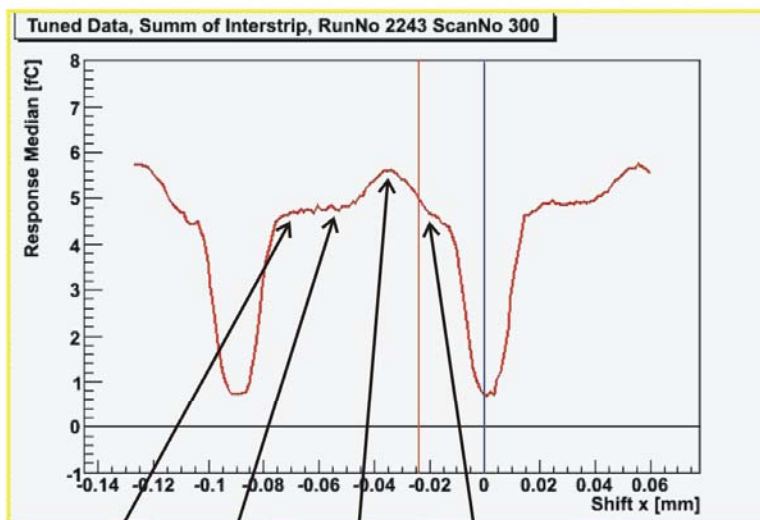




## Angle (skew) scans (2)

Tilt laser beam

Focusing to top surface from  
inside (deep focusing)

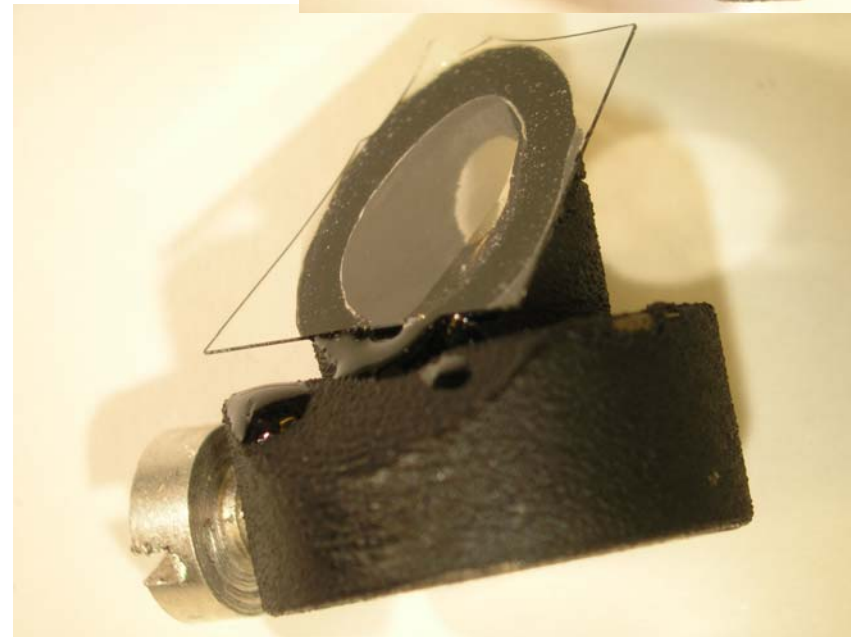
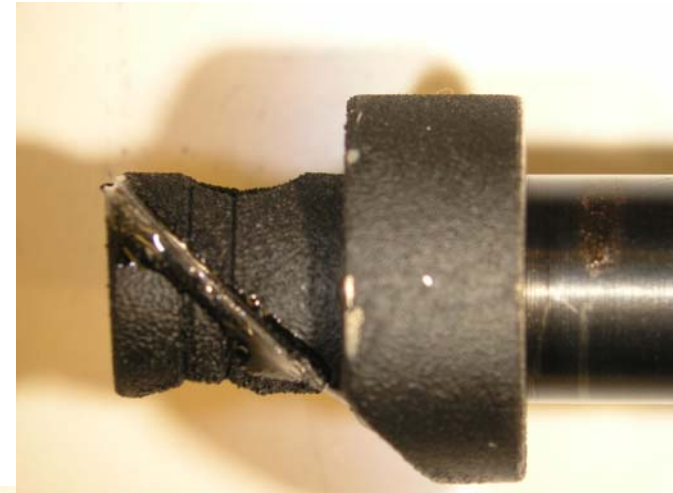
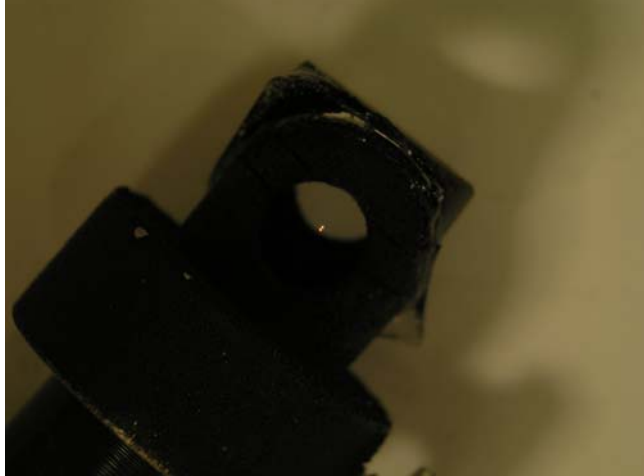
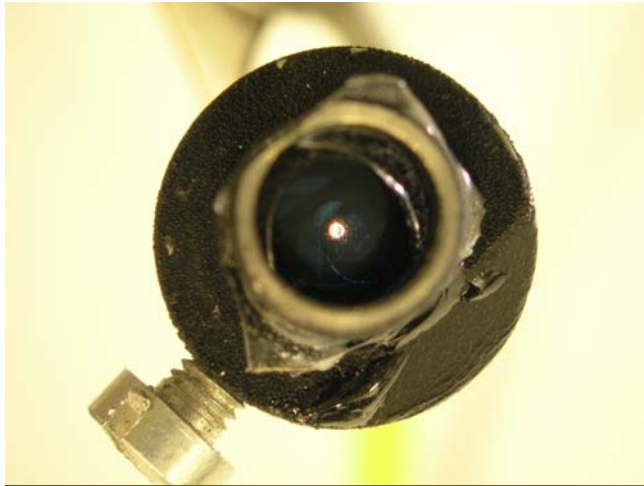






## Optical head for power monitoring and reflectance measurement

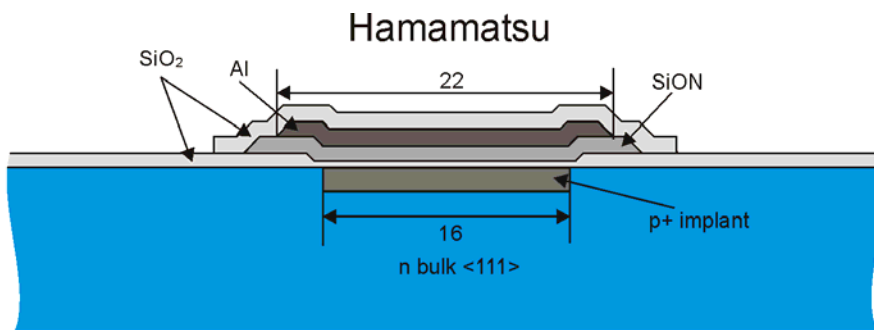
1. Mechanical design and manufacturing done
2. Readout electronics under construction



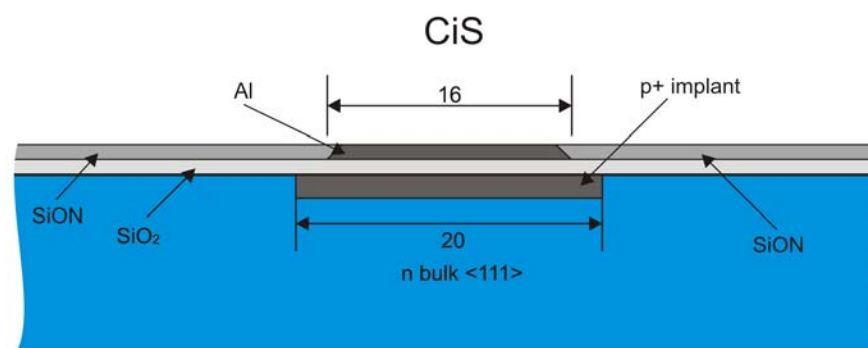
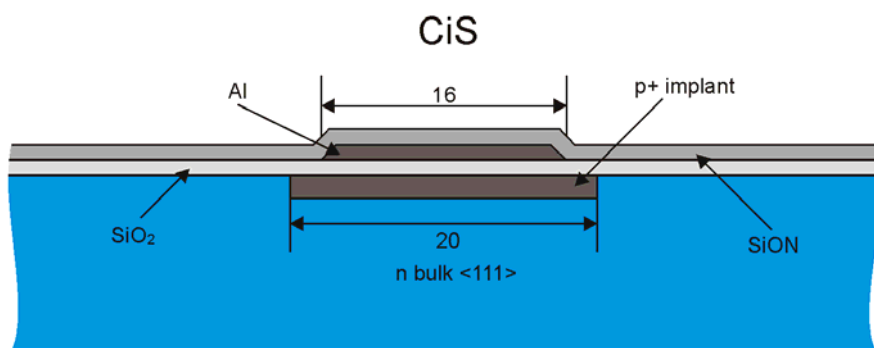
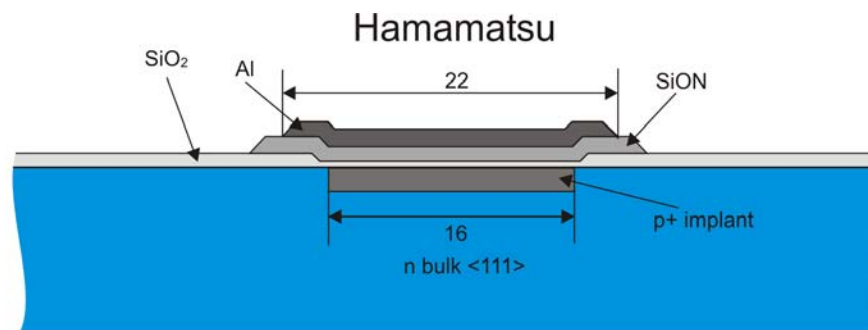


## Deeper understanding of laser beam interaction with Si detectors

Surface structure on strip



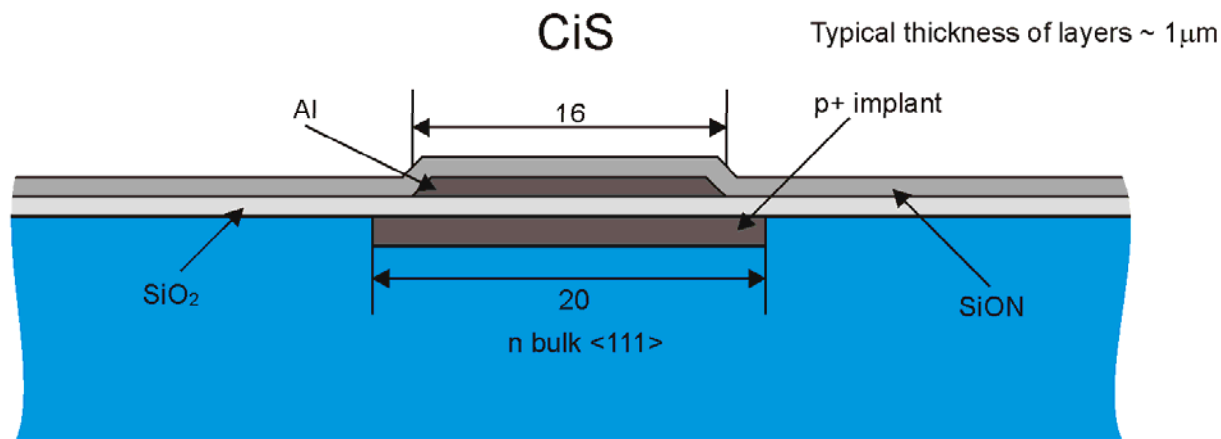
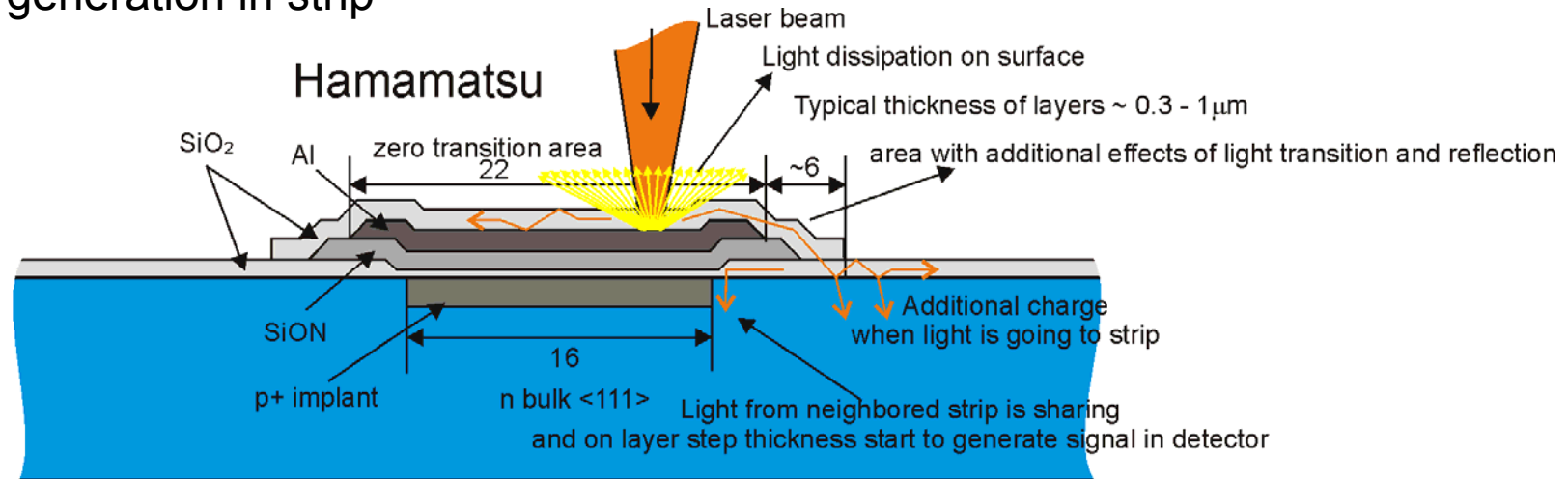
Surface structure on bond pad





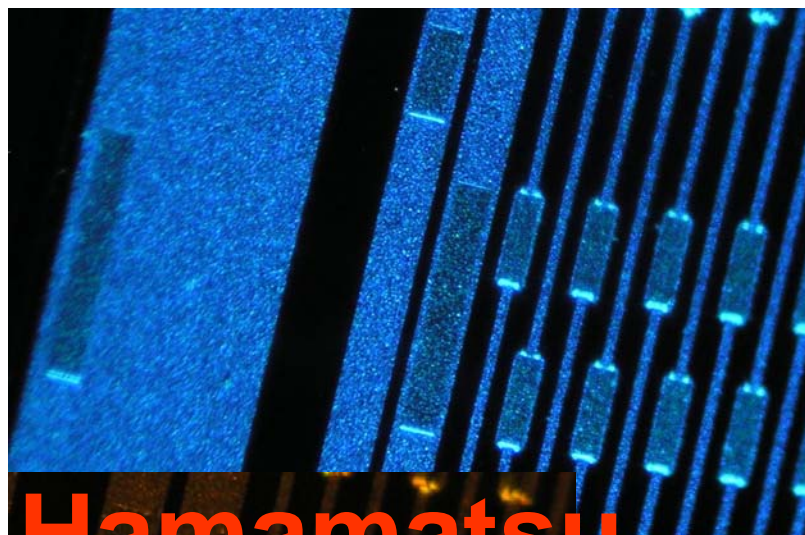
## Deeper understanding of laser beam interaction with Si detectors

### Charge generation in strip





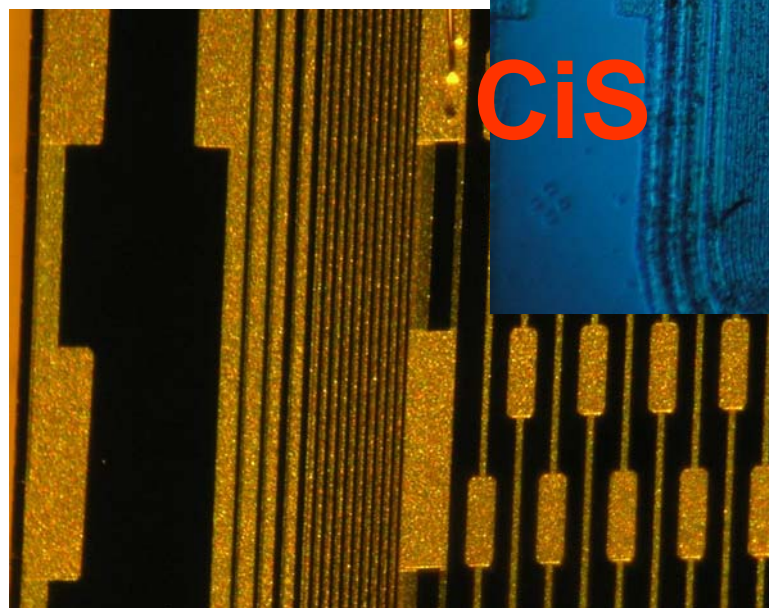
## Deeper understanding of laser beam interaction with Si detectors



1. Surface
2. Coating
3. Thickness
4. Size
5. Technology



Hamamatsu

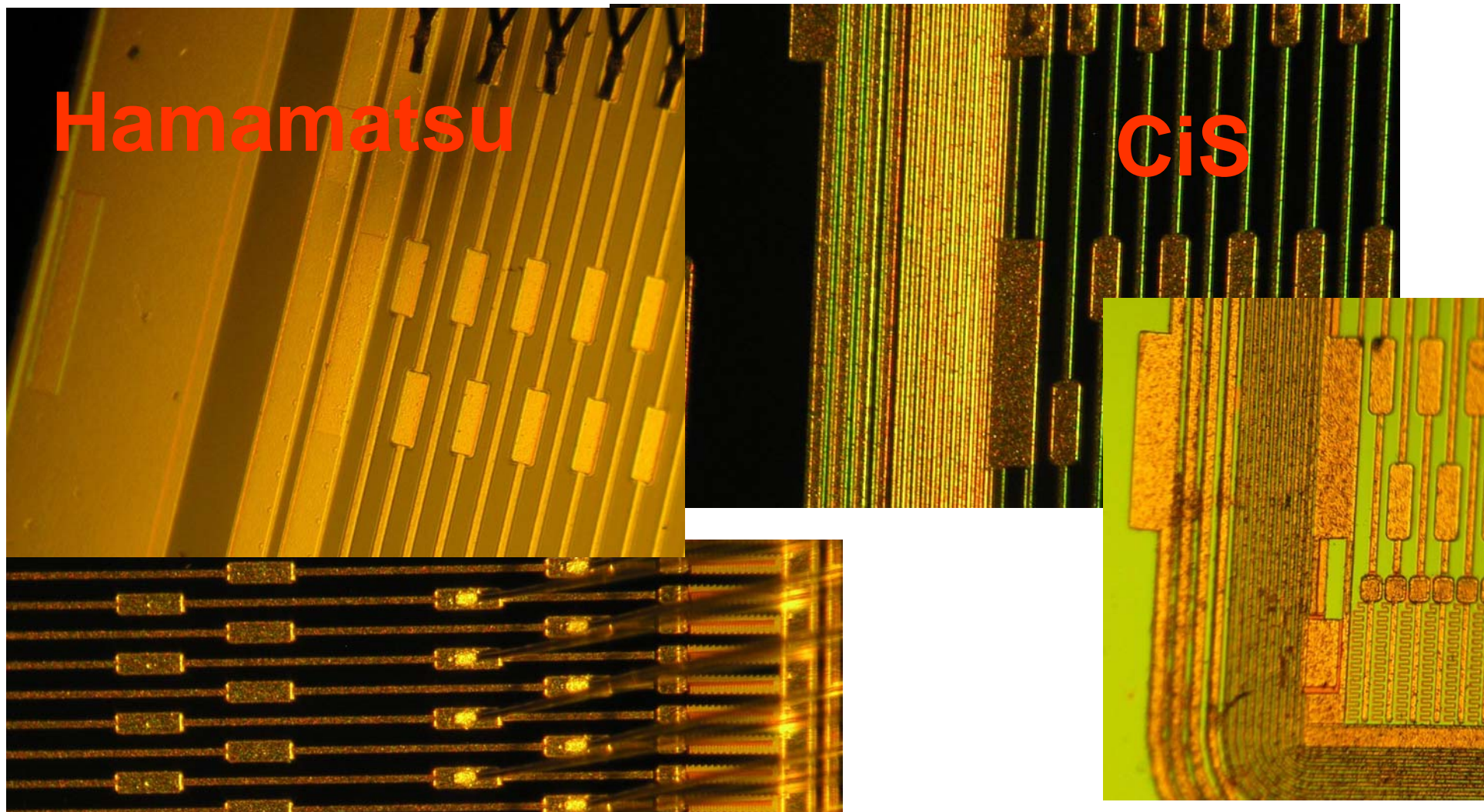


CiS



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## Deeper understanding of laser beam interaction with Si detectors



Peter Kodyš, June, 2006, RD50, Prague

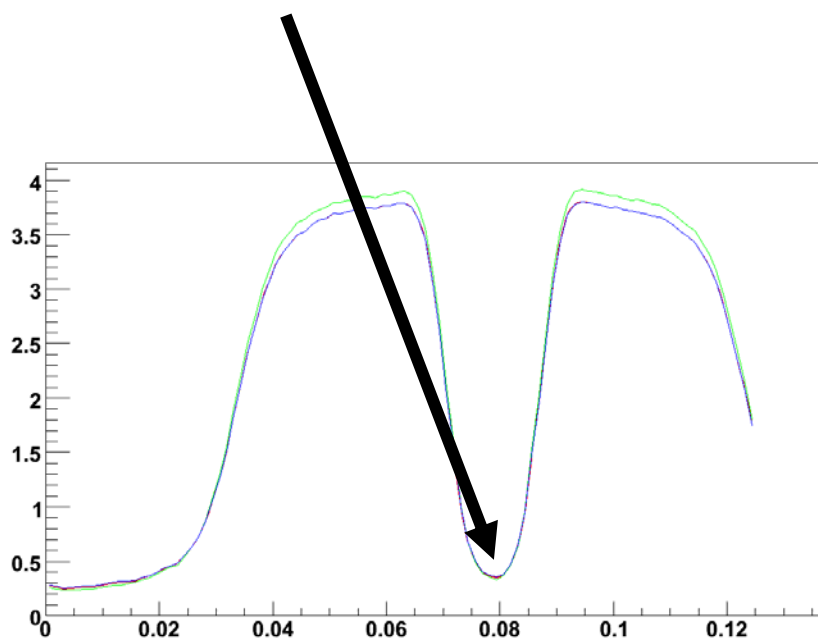
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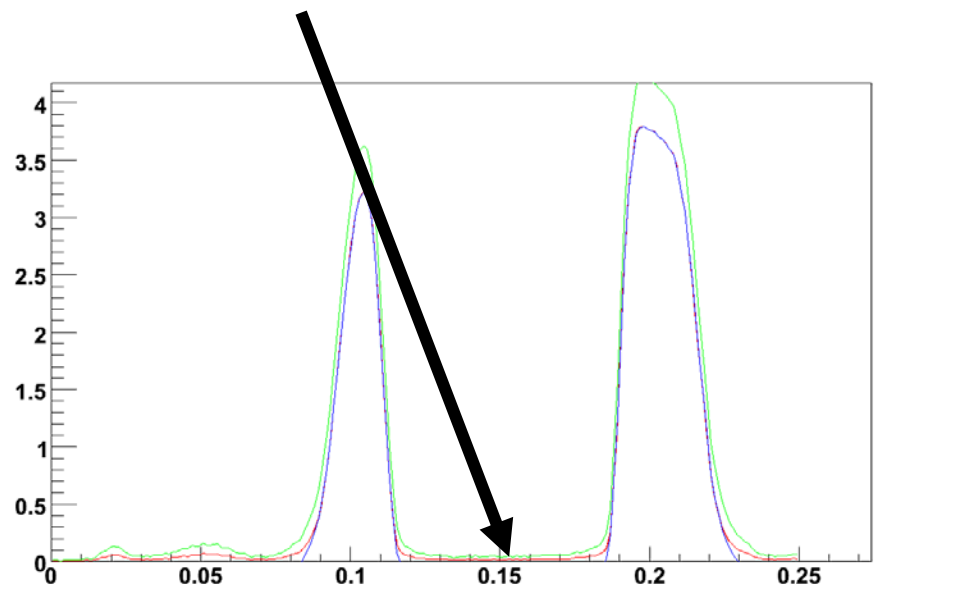
## Deeper understanding of laser beam interaction with Si detectors

# CiS

Response on strip with  
residuum charge sharing in  
protecting layer



Response on bond pad  
with no protection layers





## Deeper understanding of laser beam interaction with Si detectors

- Other possible effects influencing laser tests:
  - For 1060nm wavelength – thickness of silicon substrate changes: minima-maxima on interferences give about 30% changes in charge collection in  $\frac{1}{2}$  wavelength inside Si ( $\sim 150\text{nm}$ ) – relevant only in large area scans
  - For 650nm incomplete charge collection within integration time – charge is created in layer  $< 4\mu\text{m}$  in weak electric field – dependent also from properties of coating layers (electric field gradients, conductivities, lost charge vacancies,...)
  - Irradiated detectors: additional diffusions, inhomogeneities



## Status of laser tests technique (1)

A well-defined and cheap method of detector testing is now available.

### Main benefits:

- cheaper than standard test beams with real particles
- lightweight arrangement allowing easy transport
- generally available in labs
- good repeatability and reproducibility of results





## Status of laser tests technique (2)

### Main features and capabilities:

- fine-tuning of readout electronics, timing of signals and DAQ software tuning (algorithms, sequences, delays)
- interstrip or interpixel response with micron resolution
- response measurement - linearity, dependence on other conditions, calibrations
- measurement of pulse shapes for injected charge ranging from fractions to thousands MIPs
- injection of extra large charge for regeneration time measurement or assessment of electronics damage
- measurement of high-rate charge injection (double pulse)
- depletion voltage measurement



## Status of laser tests technique (3)

### Main features and capabilities:

- signal / noise ratio
- thermal dependencies of properties
- all previous tests also for irradiated modules (sensor or/and FE)
- thickness homogeneity of sensor with precision in 100nm range
- in combination with simulations, good insight in silicon detectors response at theoretical level